

Using the TPS65910 EVM, A Multichannel Power-management IC, 3 Buck, 1 Boost, and 8 LDOs

User's Guide



Literature Number: SWCU065E
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Introduction

1 Description

Device Description:

The TPS65910 device is an integrated power-management IC available in 48-QFN package and is dedicated to applications powered by one Li-Ion or Li-Ion polymer battery cell, 3-series Ni-MH cells, or a 5 V input, and which requires multiple power rails. The device provides three step-down converters, one step-up converter, and eight low dropout voltage regulators (LDOs) and is designed to support the specific power requirements of OMAP™ processors.

Two of the step-down converters provide power for dual processor cores and are controllable by a dedicated class-3 SmartReflex™ interface for optimum power savings. The third converter provides power for the I/Os and memory in the system. The device includes eight general-purpose LDOs providing a wide range of voltages and current capabilities. These LDOs can be controlled by the inter-integrated circuit (I²C™) interface.

In addition to the power resources, the device contains an embedded power controller (EPC) to manage the power sequencing requirements of OMAP processor and a real-time clock (RTC).

EVM Kit Description:

The TPS65910 evaluation module (EVM) is a stand-alone module that demonstrates the functions of the integrated power management IC. It uses a USB-to-GPIO interface card (not included in the kit) to control the standard I²C interfaces in the TPS65910 device. It includes Windows™-compatible software to interface with the device. The software is a simple graphical user interface (GUI) that simplifies registers access for the IC.

EEPROM Power-Up Sequence Description:

This user guide is common for all TPS65910x parts. The only difference in these parts is the EEPROM sequence for power-up. Each part has a unique EEPROM sequence to satisfy the attached application processor. For details of the EEPROM sequence please refer to the corresponding user guide in the “Application Notes” section on the TPS65910x folder page.

1.1 Applications

- Embedded application processor power
- Handheld/portable systems

1.2 Features

- An EPC
- Two efficient step-down DCDC converters for processor cores
- One efficient step-down DCDC converter for I/O power
- One efficient step-up 5-V DCDC converter
- SmartReflex-compliant dynamic voltage management for processor cores
- Eight LDO voltage regulators and one RTC LDO (internal purpose)
- One high-speed I²C interface for general-purpose control command
- One high-speed I²C interface for SmartReflex (SR) class-3 control command
- Two enable signals multiplexed with SR-I2C, configurable to control any supply state and processor cores supply voltage
- Thermal shutdown protection and hot-die detection
- An RTC resource with:
 - Oscillator for 32.768-kHz crystal or 32-kHz built-in RC oscillator
 - Complete calendar capability
 - Alarm capability
- One configurable general-purpose input/output (GPIO)
- DCDCs switching synchronization through internal or external 3-MHz clock
- Backup battery charger

2 TPS65910 EVM Power Capabilities

Table 1. TPS65910 EVM Resources Summary

POWER RESOURCE	TYPE	VOLTAGE RANGE (V)	I _{max} (mA)
VIO	SMPS (buck)	1.5, 1.8, 2.5, 3.3	1000
VDD1	SMPS (buck)	0.6, 1.1, 1.5, 2.2, 3.2	1500
VDD2	SMPS (buck)	0.6, 1.1, 1.5, 2.2, 3.2	1500
VDD3	SMPS (boost)	5	100
VDIG1	LDO	1.2, 1.5, 1.8, 2.7	300
VDIG2	LDO	1.0, 1.1, 1.2, 1.8	300
VAUX33	LDO	1.8, 2.0, 2.8, 3.3	150
VMMC	LDO	1.8, 2.8, 3.0, 3.3	300
VAUX1	LDO	1.8, 2.5, 2.8, 2.85	300
VAUX2	LDO	1.8, 2.8, 2.9, 3.3	150
VDAC	LDO	1.8, 2.6, 2.8, 2.85	150
VPLL	LDO	1.0, 1.1, 1.8, 2.5	50

For detailed electrical characteristics of SMPS and LDO supplies, refer to the product data sheet.

3 Schematic

[Figure 1](#) shows the TPS65910 EVM schematic.

The schematic diagram illustrates the internal components and connections of the TPS65910EVSM evaluation module. Key components include:

- ICs:** TPS65910RSL (Main IC), MSS1P2L (Diode), and various passive components.
- Capacitors:** C1 (0.2F), C2 (4.7uF), C3 (4.7uF), C4 (2pF), C5 (32.768 kHz), C6 (4.7uF), C7 (10uF), C8 (10uF), C9 (10uF), C10 (4.7uF), C11 (0.1uF), C12 (4.7uF), C13 (10uF), C14-C22 (2.2uF), C23 (10uF), C24 (10uF), C25 (10uF), C26 (10uF), C27 (10uF).
- Resistors:** R1 (1.5K), R2 (0), R3 (0), R4 (0), R5 (0), R6 (0), R7 (1.5K), R8 (0), R9 (0), R10 (1.5K), R11 (10K), R12 (1.5K), R13 (10K), R14 (10k).
- Inductors:** L1 (2.2uH), L2 (2.2uH), L3 (2.2uH), L4 (4.7uH).
- Connectors:** J1 (GPIO), J2 (SCLSR, SDA, SCL, SLEEP, PWRHOLD), J3 (VCC IN2), J4 (VCC IN), J5 (GND), J6 (VBAT BKUP), J7 (VDD2), J8 (VBAT), J9 (VCC IN2), J10 (VIO_OUT), J11 (VDDIO), J12 (SDA, SCLSR, SDA, SCL, SLEEP, PWRHOLD), J13 (VDDIO), J14 (VDDIO), J15 (VDDIO), J16 (VDDIO), J17 (VDDIO), J18 (VDDIO), J19 (VDDIO), J20 (VDDIO), J21 (MSS1P2L), J22 (MSS1P2L), J23 (VRRTC), J24 (VDAC), J25 (VPLL), J26 (VAUX1), J27 (VAUX2), J28 (VMMC), J29 (VAUX3), J30 (VDIG1), J31 (VDIG2), J32 (LDO GND), J33 (VDD3), J34 (VDD1), J35 (VDD2), J36 (VDD2), J37 (VDD2), J38 (VDD2), J39 (VIO_OUT), J40 (VIO_OUT).
- Test Points:** TP1, TP2, TP3, TP4, TP5, TP6.

The diagram is organized into a grid with columns A-F and rows 1-4. A legend indicates that triangles represent components not used, and a note states that C3 is not needed if connected to VDDIO.

Texas Instruments			
Title: TPS65910EVSM			
Size: C	Number: HPA583	Rev: A	
Date: Tue Nov 09, 2010	Drawn by: KLL		
Filename: HPA583A.sch	Sheet: 1 of 1		

4 Connector and Test Point Descriptions

4.1 Connector Descriptions

4.1.1 Boot Pins

J16 and J17 are used to select the boot pin configuration for proper booting of the device. [Table 2](#) shows the possible boot options.

Table 2. Boot Configuration

BOOT 0	BOOT 1	POWER UP OPTION
0	0	AM35xx
0	1	EEPROM boot mode
1	0	OMAP3x
1	1	Test mode only

4.1.2 Backup Battery

J6 is used for the backup battery connection. The user can connect a backup battery between J6-2 and J6-3 or alternatively can use the onboard 0.2 F, 3.3 V capacitor by shorting J6-1 and J6-2.

4.1.3 VBAT

VBAT (J4) is the main input source to the device. [Table 3](#) lists the minimum and maximum levels that can be applied to these pins. Use J5 for ground.

Table 3. VBAT Minimum and Maximum Levels

VBAT	MIN (V)	TYP (V)	MAX (V)
	2.7	3.6	5.5

Ensure that the jumper settings for the jumpers listed in [Table 4](#) are correct so the device is supplied by VBAT.

Table 4. VBAT Input Jumper Settings

JUMPER CONNECTION	DEVICE INPUT PIN	USE
J7 (1-2)	VCC5	Selects VBAT as power source
J8 (1-2)	VCC3	Selects VBAT as power source
J9 (1-2)	VCC2, VCC4	Selects VBAT as power source
J10 (2-3)	VCC6	Selects VBAT as power source

4.1.4 Default Jumper Settings for the Boost Converter

Table 5. Boost Converter Jumper Settings

JUMPER ID	LABEL	USE
J21	SW3	Short jumper to use boost converter
J22	VFB3	Short jumper to use boost converter

For correct functioning of VDD3, first VAUX33 must be enabled at 3.3V and then VDD3 should be enabled using the appropriate register settings.

4.1.5 I²C connector

TPS65910 has two slave I²C interfaces: one is a general-purpose interface to control the internal configuration registers, the second is dedicated to SmartReflex applications such as dynamic voltage frequency scaling (DVFS) or adaptive voltage scaling (AVS).

These interfaces support the standard slave mode (100 kbps), fast mode (400 kbps), and high-speed mode (3.4 Mbps).

Table 6. I²C Connector

CONNECTOR NUMBER	PIN	DESCRIPTION
J1	9, 10	General purpose I ² C interface for register configuration
J2	9,10	Dedicated I ² C interface for SmartReflex

J1 and J2 also have GPIO, SLEEP, and PWRHOLD signals that can be controlled from the GUI and USB-to-GPIO interface.

The SmartReflex can be programmed as enable signals of one or several supplies when the device is on. A resource assigned to either SmartReflex signal (SDASR_EN2 or SCLSR_EN1) automatically disables the serial control interface.

Connectors J1 and J2 are used for the USB adapter. [Table 7](#) lists the signal mapping to control the signals on the EVM. The GPIO field on the GUI can be toggled to drive the following signals on the EVM.

Table 7. GPIO Mapping For GUI

PIN NUMBER FOR J1 and J2	GPIO ON GUI	TPS65910x SINGAL
Pin 1	GPIO7	SLEEP
Pin 2	GPIO6	GPIO
Pin 3	GPIO5	PWRHOLD

4.1.6 3.3-V I/O for VDDIO

The USB-to-GPIO interface is on connectors J1 and J2. The USB-to-GPIO module generates 3.3 V, which is used as the I/O for the EVM. The following jumper configuration must be done for the I/O supply.

Table 8. Jumper for I/O Input Setting

JUMPER CONNECTION	DEVICE INPUT PIN	USE
J11 (1-2)	VDDIO	Connects J1-5 (or J2-5) to VDDIO for 3.3-V I/O input

4.1.7 Control Jumper Settings

TPS65910 has some control signals that can be configured using the on-board jumpers or by using the USB-to-GPIO connector.

Table 9. Control Signals

Jumper connection	Signal Name	Use
J18	GPIO	Jumper the three pin connector as required
J19	SLEEP	Jumper the three pin connector as required
J20	PWRHOLD	If PWRHOLD is low then the device will not power-up. So, connect this to HI side of the jumper. See important description below.
J13	SDASR_EN2	Both these signals can be used to control the LDO and SMPS power supplies. Please refer details on programming the internal register to achieve this function.
J14	SCLSR_EN1	

If USB-to-GPIO connector is connected on J1 or J2 then the above signals can be controlled using the GPIO writes from the GUI. In this case the above jumpers should not be connected. Jumpers should be left open. In case of SLEEP and GPIO signals there will be contention for VDDIO supply. In case of PWRHOLD, the device will be damaged. This is because the PWRHOLD signal from USB-to-GPIO is at 3.3V. The HI side of J20 jumper is connected to VRRTC. If VRRTC is shorted to 3.3V then this will damage the device. When the adapter is connected all IOs should be at 3.3V, so ensure J11 is connected between VDDIO and 3.3V.

4.2 Test Point Descriptions

Table 10. Test Point Descriptions

Power Domain/Control	TP	Label	Use
VIO	J39	VIO_OUT	Monitor VIO output voltage
VDD1	J35	VDD1	Monitor VDD1 output voltage
VDD2	J37	VDD2	Monitor VDD2 output voltage
VDD3	J33	VDD3	Monitor VDD3 output voltage
VPLL	J25	VPLL	Monitor VPLL output voltage
VDAC	J24	VDAC	Monitor VDAC output voltage
VAUX1	J26	VAUX1	Monitor VAUX1 output voltage
VAUX2	J27	VAUX2	Monitor VAUX2 output voltage
VMMC	J28	VMMC	Monitor VMMC output voltage
VAUX33	J29	VAUX33	Monitor VAUX33 output voltage
VDIG1	J30	VDIG1	Monitor VDIG1 output voltage
VDIG2	J31	VDIG2	Monitor VDIG2 output voltage
VREF	J15	VREF	Monitor VREF output voltage
VRRTC	J23	VRRTC	Monitor VRRTC output voltage
PWRHOLD	J20-2	PWRHOLD	Monitor PWRHOLD level
PWON	S1	POWER ON	Power-on switch
SLEEP	J19-2	SLEEP	Control device status
GPIO/CKSYN	J18-2	GPIO/CKSYNC	GPIO test point
NRESPWON	TP5	NRESPWON	Reset to processor
INT1	TP4	INT1	Interrupt to processor
CLK32KOUT	TP6	CLK32KOUT	32KHz to processor

Use J32 for all GND connections for measuring the LDO power supplies. J34, J36, J38, and J40 can be used for ground connections for measuring DCDC power supplies.

5 Test Set Up

5.1 Equipment

Recommended test equipments:

- Variable 6-V power supply capable of supplying 6 A current
- Voltmeter
- Oscilloscope
- Windows PC with a universal serial bus (USB) port
- USB-to-GPIO converter

6 GUI Information

The GUI accompanying this device is fairly simple. It runs on a Windows PC. Ensure that your machine supports Microsoft .NET Framework 3.5.

6.1 *Installation Instructions:*

To install the GUI follow these steps:

1. Download from site/Insert CD (based on how we package the GUI).
2. Create a new folder or unzip into any appropriate windows folder. If it is an exe, then select the location. The default is C:/xyz/.

6.2 *Know the Files*

GUI software consists of the following files:

- DLL
- EXE
- XML

The GUI can be opened by clicking the MS Installer, TPS65910.msi file. The .xml file is the main file that contains all the device registers. The registers in this file are categorized in blocks according to the functions. The .xml file also specifies the slave I²C address for the device.

6.3 *GUI Description*

GUI windows are divided into the following sections:

6.3.1 *Register Properties*

The following blocks are on the GUI on the left-side pane under Register Properties:

- Time and Calendar Registers
- RTC Registers
- Back-up Registers
- DCDC Control Registers
- LDO Control Registers
- Device Control Registers
- Interrupts and GPIO Registers

[Figure 2](#) shows a sample snapshot of the GUI.

Each block can be selected independently so that it appears on the main GUI window. Each register instance appears in a separate block. See [Figure 3](#).

The user can write to the registers through the I²C bus. Each bit in the 8-bit register can be written independently or the complete register can be written using an 8-bit hexadecimal value in the Value field. Individual bits can be toggled either by selecting the drop-down menu or by double-clicking the field.

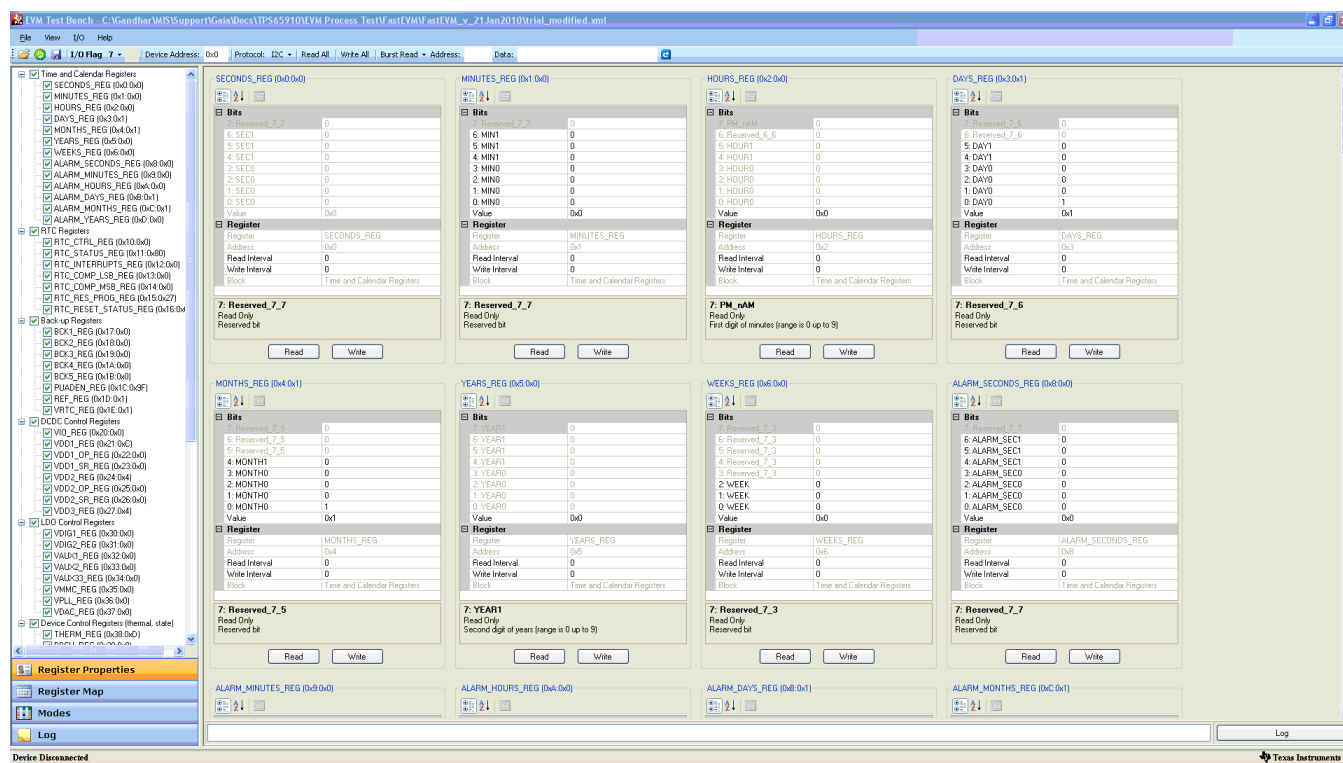


Figure 2. GUI Snapshot – Register Properties

SWCU065-002



Figure 4 shows the register map view. The Register Map tab provides an alternative way to access the device registers. Also in this view, the bits and complete words can be read or written through the I²C bus.

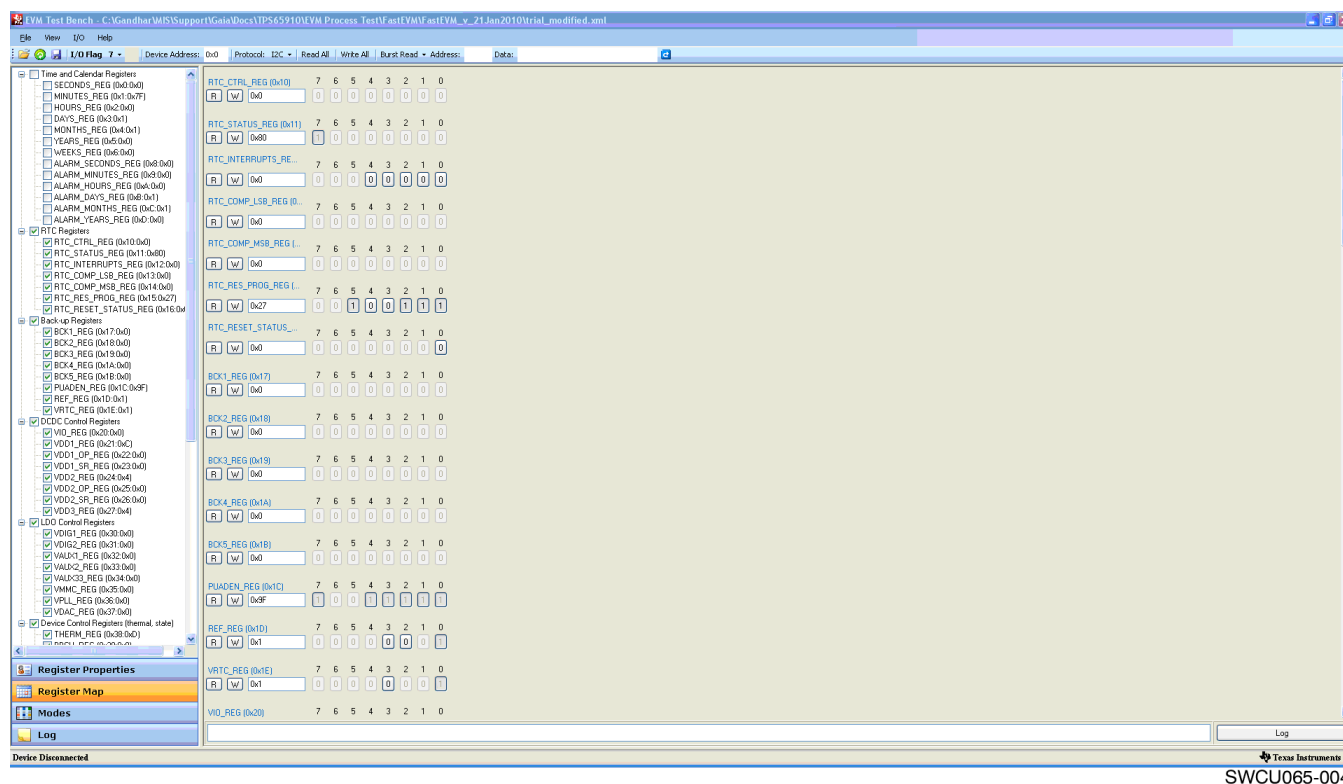


Figure 4. Register Map View

6.3.3 Modes

This section is used for executing multiple register writes in a single step. For example, to configure the device in SLEEP state, multiple bits must be configured for SMPS and LDO supplies. An example is provided in the .xml file that comes with the GUI package.

Users can create their own sequences in the .xml file.

6.3.4 I/O writes

Three control signals for the TPS65910 (SLEEP, PWRHOLD and GPIO) can be altered using the GUI. To select these signals, the user can use the I/O Flag tab on the menu bar. For mapping of the I/O lines, refer to the TPS65910 schematic and datasheet for the GPIO-to-USB adapter at <http://focus.ti.com/docs/toolsw/folders/print/usb-to-gpio.html>.

7 EVM Assembly Drawings and Layout

The following figures show the design of the TPS65910 EVM printed circuit board. The EVM has been designed using a 4-layer, 2-ounce, 4-inch × 4-inch copper-clad circuit board with all components on the top side and all active traces to the top to let the user easily view, probe, and evaluate the TPS65910 IC.

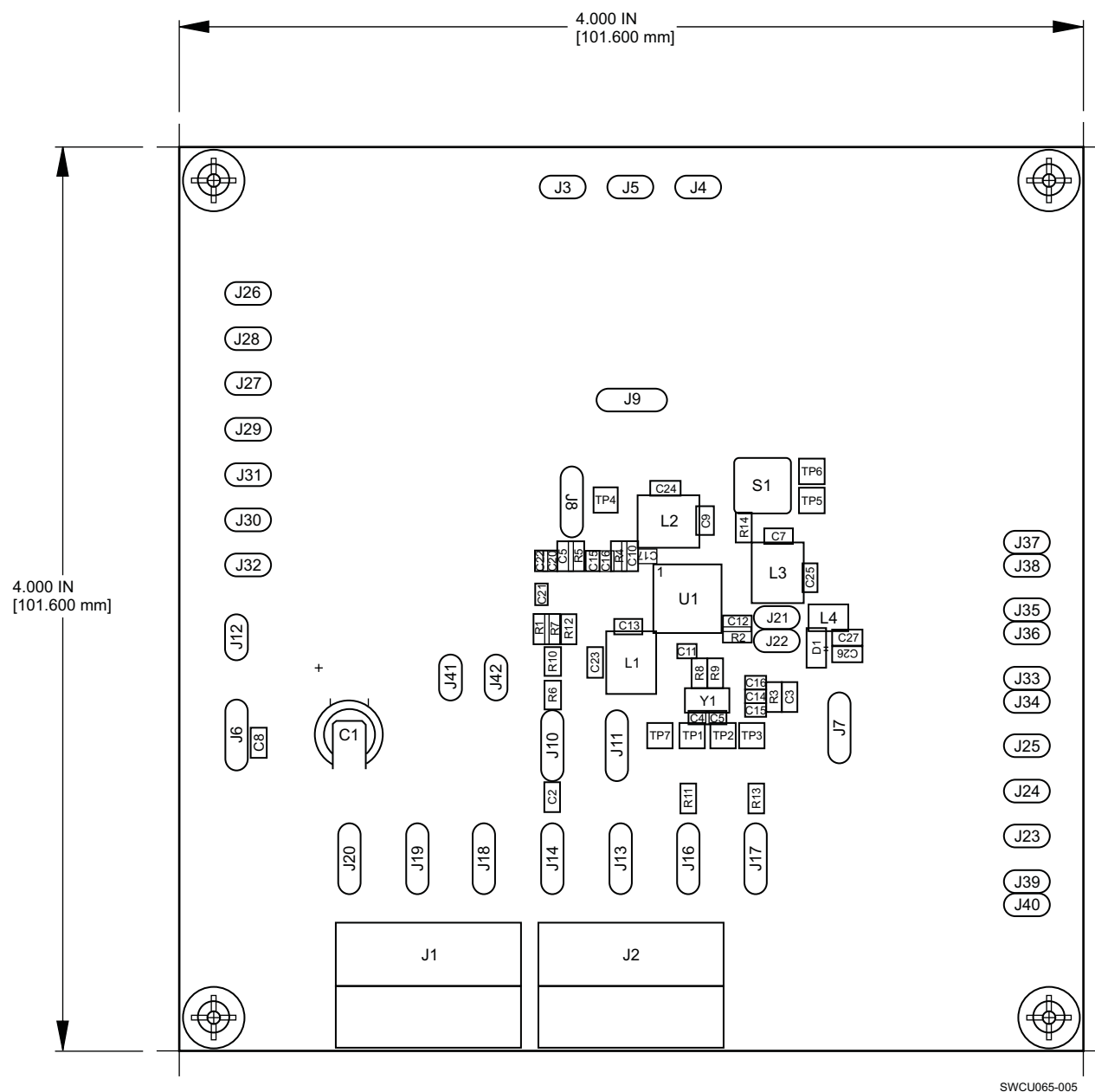


Figure 5. TPS65910 EVM Component Placement With Silkscreen Labels

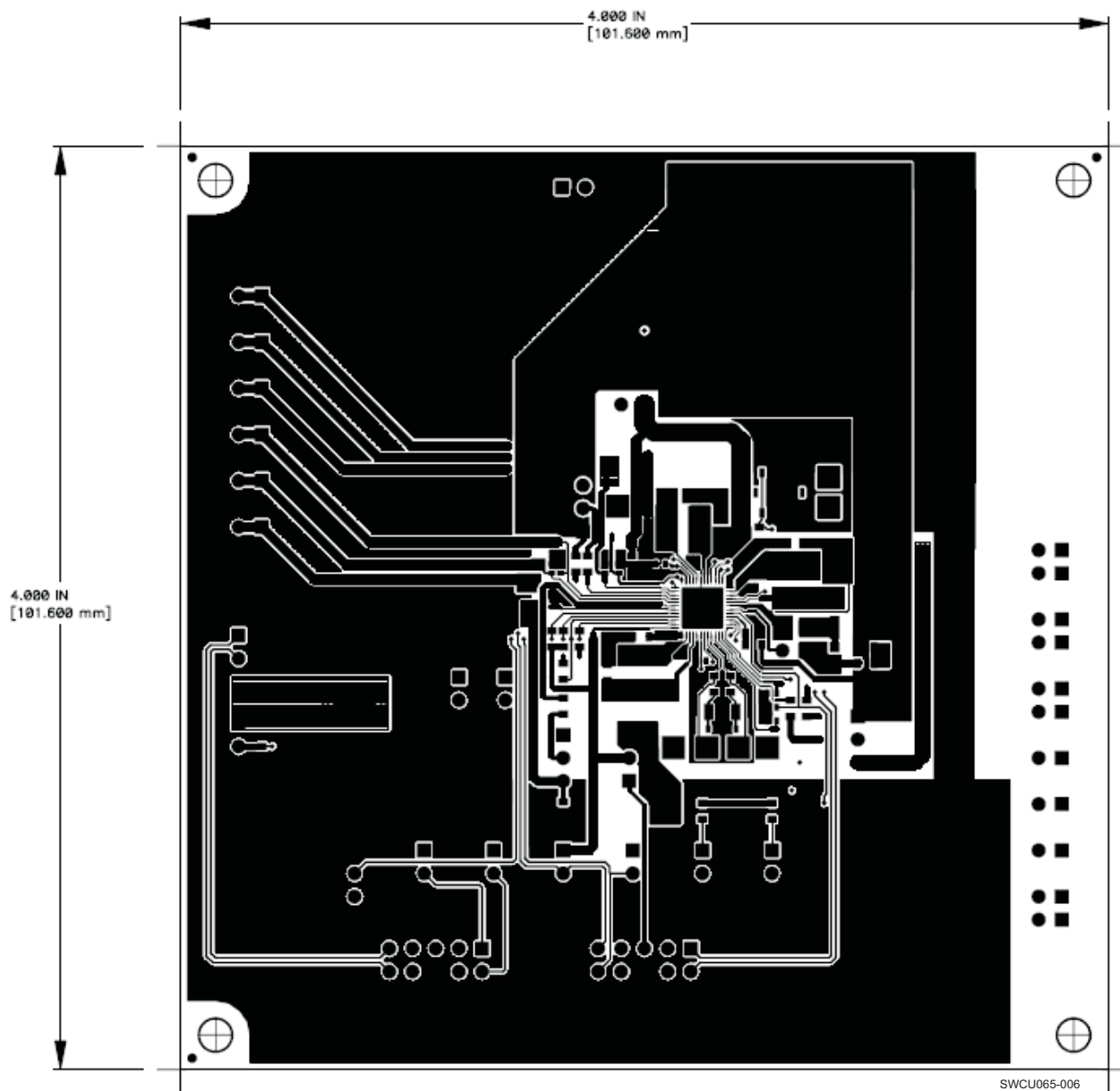


Figure 6. TPS65910 EVM Top Layer (L1)

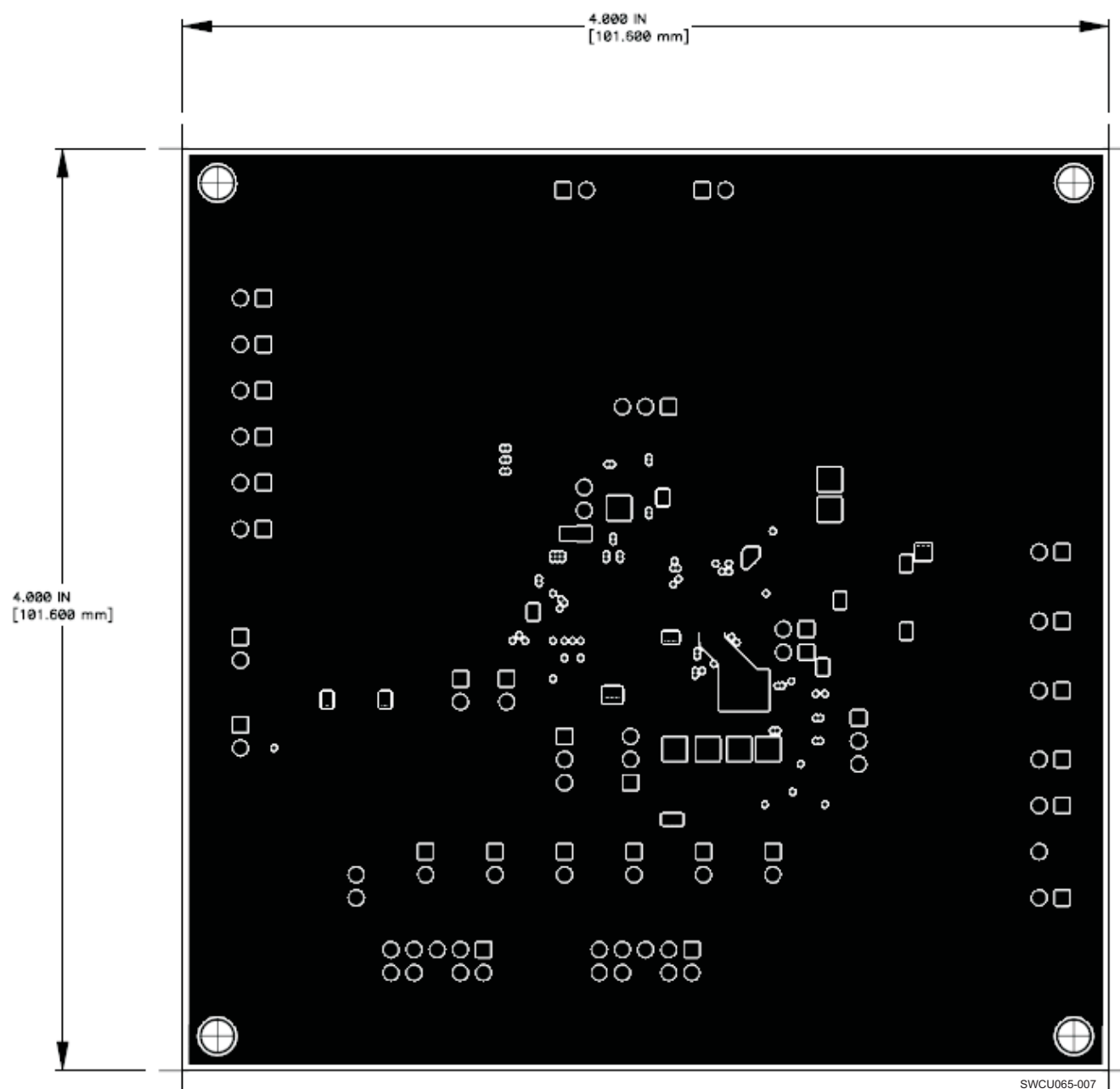


Figure 7. TPS65910 EVM Internal Layer (L2)

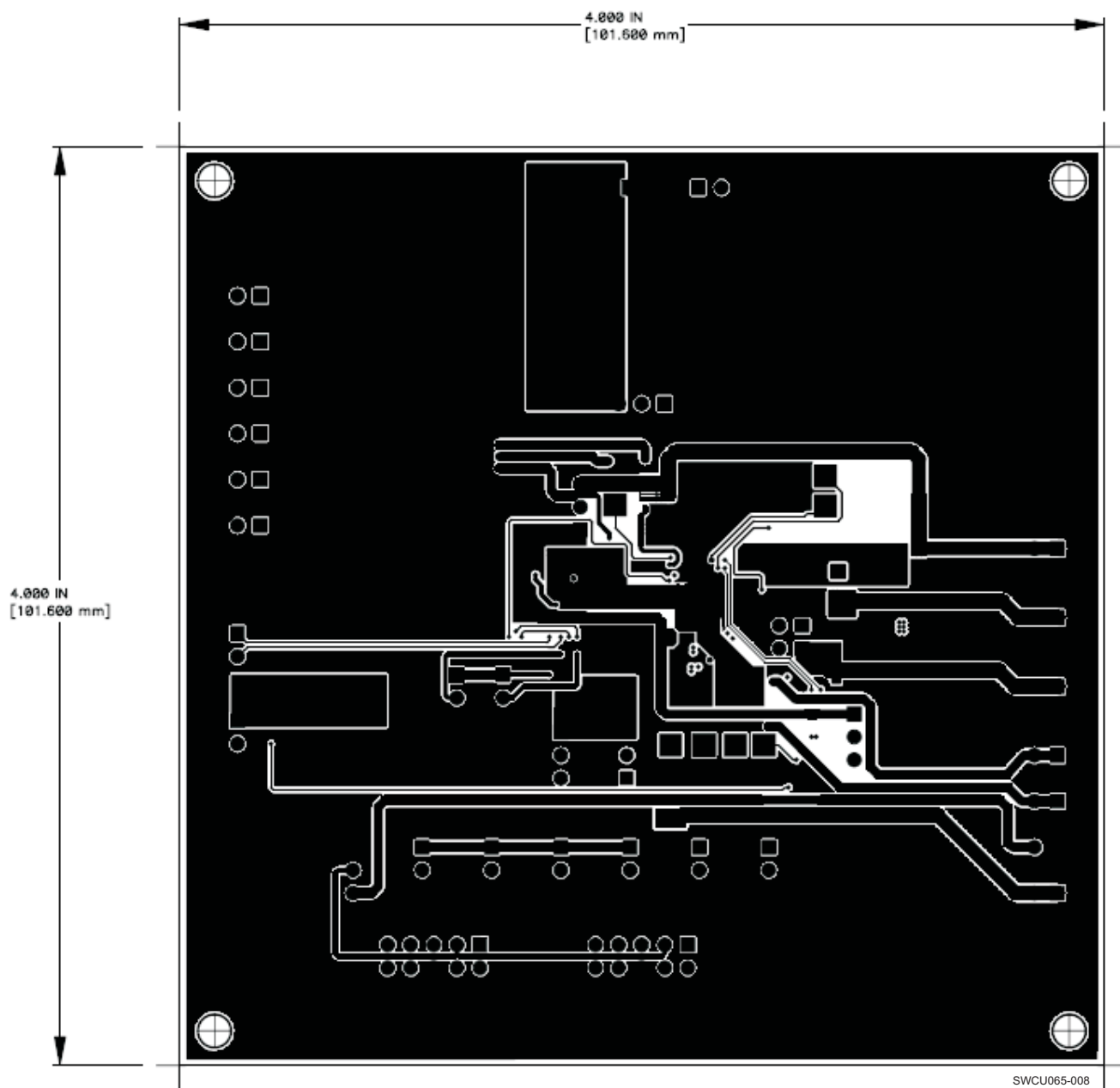


Figure 8. TPS65910 EVM Internal Layer (L3)

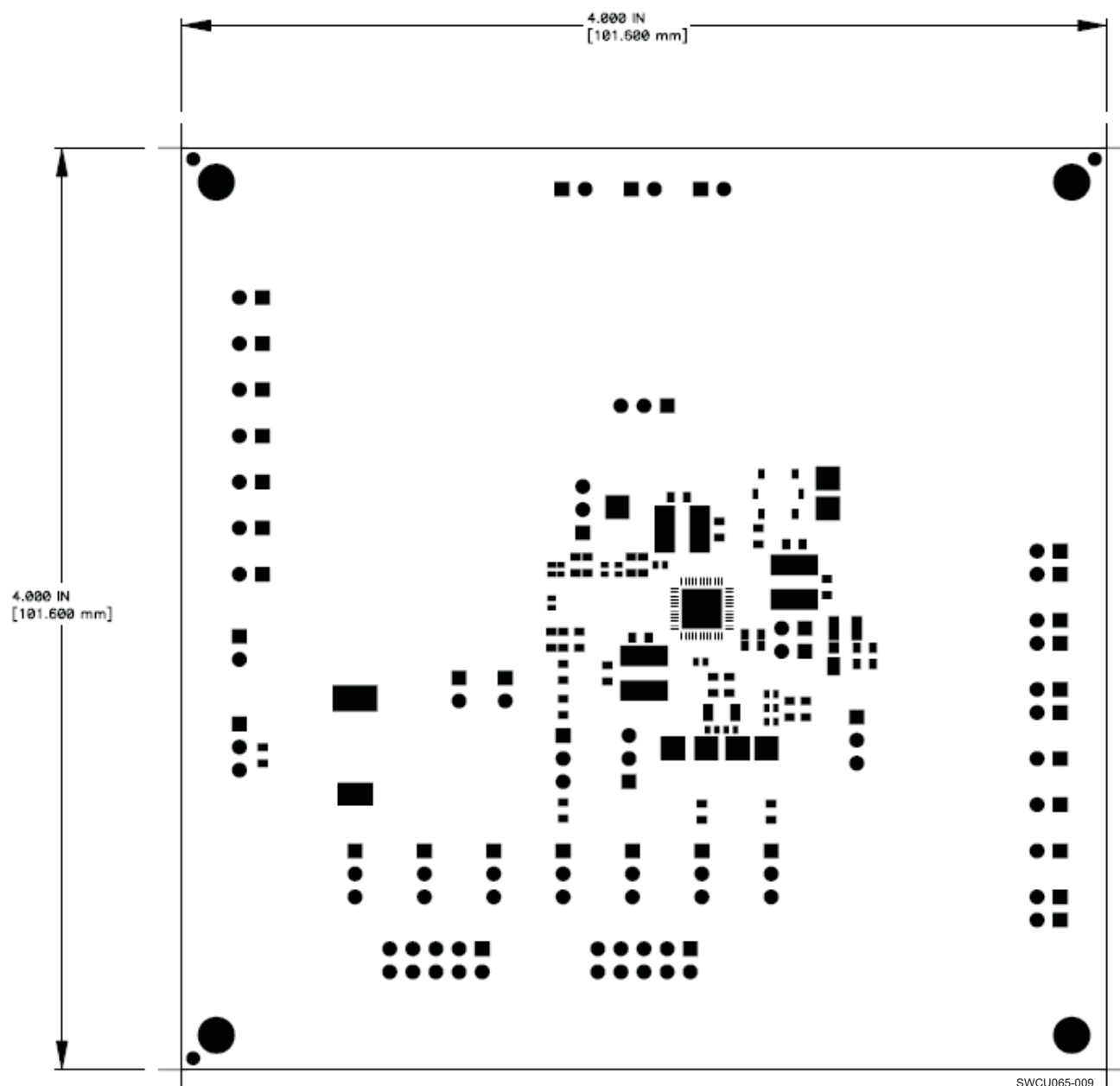


Figure 9. TPS65910 EVM Bottom Copper (L4)

8 List of Materials

Table 11 lists the EVM components as configured according to the schematic shown in Figure 1.

Table 11. TPS65910 EVM Bill of Materials

COUNT	REFDES	VALUE	DESCRIPTION	SIZE	PART NUMBER	MFR
1	C1	0.2 F	Capacitor, Electric Double Layer	AK	EECEN0F204AK	Panasonic
1	C11	0.10 μ F	Capacitor, Ceramic, 10 V, X5R, 10%	0402	STD	{MFR}
9	C14, C15, C16, C17, C18, C19, C20, C21, C22	2.2 μ F	Capacitor, Ceramic, 6.3 V, X5R, 20%	0402	JMK105BJ225M V-F	Taiyo Yuden
5	C2, C3, C6, C10, C12	4.7 μ F	Capacitor, Ceramic, 6.3 V, X5R, 20%	0603	JMK107BJ475K A-T	Taiyo Yuden
2	C4, C5	12 pF	Capacitor, Ceramic, vvV, [temp], [tol]	0402	{Part Number}	{MFR}
9	C7, C8, C9, C13, C23, C24, C25, C26, C27	10 μ F	Capacitor, Ceramic, 6.3 V, X5R, 20%	0603	C0603C106M9P AC	Kemet
1	D1	MSS1P2L	Diode, Schottky, 20 V, 1 A	MicroSMP	MSS1P2L	Vishay
2	J1, J2	2510-5002UB	Connector, Male Right Angle 2x5 pin, 100 mil spacing, 4 Wall	0.100 inch x 2X5	2510-5002UB	3M
26	J3, J4, J5, J12, J21, J22, J23, J24, J25, J26, J27, J28, J29, J30, J31, J32, J33, J34, J35, J36, J37, J38, J39, J40, J41, J42	PEC02SAAN	Header, Male 2-pin, 100 mil spacing	0.100 inch x 2	PEC02SAAN	Sullins
13	J6, J7, J8, J9, J10, J11, J13, J14, J16, J17, J18, J19, J20	PEC03SAAN	Header, Male 3-pin, 100 mil spacing	0.100 inch x 3	PEC03SAAN	Sullins
3	L1, L2, L3	2.2 μ H	Inductor, SMT, 2.6 A, 58 m Ω	0.157 x 0.157 inch	VLCF5020T- 2R2N2R6-3	TDK
1	L4	4.7 μ H	Inductor, SMT Multi-layer, 1 A, 110 m Ω	2520 mm	MIPF2520D4R7 S	FDK
					Alternate part:	
					LQM2HPN4R7M G0L	Murata
4	R1, R7, R10, R12	1.5 k Ω	Resistor, Chip, 1/16 W, 5%	0603	STD	STD
2	R11, R13	10 k Ω	Resistor, Chip, 1/16 W, 5%	0603	STD	STD
	R14	10 k Ω	Resistor, Chip, 1/16 W, 5%	0603	STD	STD
7	R2, R3, R4, R5, R6, R8, R9	0	Resistor, Chip, 1/16 W, 5%	0603	STD	STD
1	S1	EVQ-PLHA15	Switch, 1P1T, 50 mA, 12 V, 160 g	0.200 x 0.200 inch	EVQ-PLHA15	Panasonic
1	SH1		Short jumper			

Table 11. TPS65910 EVM Bill of Materials (continued)

COUNT	REFDES	VALUE	DESCRIPTION	SIZE	PART NUMBER	MFR
7	TP1, TP2, TP3, TP4, TP5, TP6, TP7	PEC01SAAN	Through Hole, 0.040 Diameter		PEC01SAAN	Sullins
1	U1	TPS65910RSL	IC, Integrated Power Management	QFN	TPS65910RSL	TI
1	Y1	32.768 kHz	Crystal	1.50 x 3.20 mm	FC-135	Epson Toyocom

NOTE: These assemblies are ESD sensitive, ESD precautions must be observed.

These assemblies must be clean and free from flux and all contaminants. Use of contaminated flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2.

Reference designators marked with an asterisk (**) cannot be substituted. All other components can be substituted with equivalent manufacturer's components.

EVALUATION BOARD/KIT/MODULE (EVM) ADDITIONAL TERMS

Texas Instruments (TI) provides the enclosed Evaluation Board/Kit/Module (EVM) under the following conditions:

The user assumes all responsibility and liability for proper and safe handling of the goods. Further, the user indemnifies TI from all claims arising from the handling or use of the goods.

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As noted in the EVM User's Guide and/or EVM itself, this EVM and/or accompanying hardware may or may not be subject to the Federal Communications Commission (FCC) and Industry Canada (IC) rules.

For EVMs **not** subject to the above rules, this evaluation board/kit/module is intended for use for ENGINEERING DEVELOPMENT, DEMONSTRATION OR EVALUATION PURPOSES ONLY and is not considered by TI to be a finished end product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC or ICES-003 rules, which are designed to provide reasonable protection against radio frequency interference. Operation of the equipment may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

General Statement for EVMs including a radio

User Power/Frequency Use Obligations: This radio is intended for development/professional use only in legally allocated frequency and power limits. Any use of radio frequencies and/or power availability of this EVM and its development application(s) must comply with local laws governing radio spectrum allocation and power limits for this evaluation module. It is the user's sole responsibility to only operate this radio in legally acceptable frequency space and within legally mandated power limitations. Any exceptions to this are strictly prohibited and unauthorized by Texas Instruments unless user has obtained appropriate experimental/development licenses from local regulatory authorities, which is responsibility of user including its acceptable authorization.

For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

For EVMs annotated as IC – INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concerning EVMs including detachable antennas

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l'autorité de l'utilisateur pour actionner l'équipement.

Concernant les EVMs avec appareils radio

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

【Important Notice for Users of this Product in Japan】

This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

1. Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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EVALUATION BOARD/KIT/MODULE (EVM) WARNINGS, RESTRICTIONS AND DISCLAIMERS

For Feasibility Evaluation Only, in Laboratory/Development Environments. Unless otherwise indicated, this EVM is not a finished electrical equipment and not intended for consumer use. It is intended solely for use for preliminary feasibility evaluation in laboratory/development environments by technically qualified electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems and subsystems. It should not be used as all or part of a finished end product.

Your Sole Responsibility and Risk. You acknowledge, represent and agree that:

1. You have unique knowledge concerning Federal, State and local regulatory requirements (including but not limited to Food and Drug Administration regulations, if applicable) which relate to your products and which relate to your use (and/or that of your employees, affiliates, contractors or designees) of the EVM for evaluation, testing and other purposes.
2. You have full and exclusive responsibility to assure the safety and compliance of your products with all such laws and other applicable regulatory requirements, and also to assure the safety of any activities to be conducted by you and/or your employees, affiliates, contractors or designees, using the EVM. Further, you are responsible to assure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard.
3. You will employ reasonable safeguards to ensure that your use of the EVM will not result in any property damage, injury or death, even if the EVM should fail to perform as described or expected.
4. You will take care of proper disposal and recycling of the EVM's electronic components and packing materials.

Certain Instructions. It is important to operate this EVM within TI's recommended specifications and environmental considerations per the user guidelines. Exceeding the specified EVM ratings (including but not limited to input and output voltage, current, power, and environmental ranges) may cause property damage, personal injury or death. If there are questions concerning these ratings please contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, some circuit components may have case temperatures greater than 60°C as long as the input and output are maintained at a normal ambient operating temperature. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors which can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during normal operation, please be aware that these devices may be very warm to the touch. As with all electronic evaluation tools, only qualified personnel knowledgeable in electronic measurement and diagnostics normally found in development environments should use these EVMs.

Agreement to Defend, Indemnify and Hold Harmless. You agree to defend, indemnify and hold TI, its licensors and their representatives harmless from and against any and all claims, damages, losses, expenses, costs and liabilities (collectively, "Claims") arising out of or in connection with any use of the EVM that is not in accordance with the terms of the agreement. This obligation shall apply whether Claims arise under law of tort or contract or any other legal theory, and even if the EVM fails to perform as described or expected.

Safety-Critical or Life-Critical Applications. If you intend to evaluate the components for possible use in safety critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, such as devices which are classified as FDA Class III or similar classification, then you must specifically notify TI of such intent and enter into a separate Assurance and Indemnity Agreement.

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